



REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	CHRIS P.	06-03-16

## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
  2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
  3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
  4. INSTALL SHUNTS AS SHOWN.
  5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
  6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
  7. INSTALL STANDOFFS AS SHOWN BELOW:
- PCB : TOP
- PCB : BOTTOM
- MH1-MH4  
4 X STANDOFF  
NYLON, SNAP ON.
8. J13, J16, J17, AND J18 ARE MOUNTED ON THE TOP SIDE. DO NOT CUT J13, J16, J17, AND J18'S LONG LEGS ON THE BOTTOM SIDE.
  - J11 IS MOUNTED ON THE BOTTOM SIDE. DO NOT CUT J11'S LONG LEGS ON THE TOP SIDE.

## APPROVALS

PCB DES.	KIM T.
APP ENG.	CHRIS P.



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FOR CUSTOMER USE ONLY

TITLE: TOP ASSEMBLY DRAWING

LINDUINO SPI 1:8 EXPANDER SHIELD

SIZE	IC NO.	REV.
N/A	DEMO CIRCUIT 2430A	2

SCALE = NONE

FILENAME: DC2430A-2.PCB

SHT 1 OF 2